ABSTRACT

Microwave package with surface mounting and corresponding mounting with a multilayer circuit

The invention relates to a microwave package delimiting an interior volume, comprising at least:

- a Faraday cage formed by a conducting surface (1, 5, 3e) surrounding the interior volume,
- a connection point (8a) placed outside the Faraday cage, the connection point being intended to be linked electrically to an exterior circuit,
- an input-output passing through the Faraday cage and linked electrically to the connection point,
- a base (3) forming a face of the package, the exterior surface of the base forming a mounting surface intended to be applied to the exterior circuit, the connection point being placed on the mounting surface, so that the connection point is placed between the Faraday cage and the exterior circuit when the package is mounted on the exterior circuit.

The invention applies to microwave packages used in the realms of avionics, telecommunications, space.

Figure 1